

# MMBF5457LT1

Preferred Device

## JFET - General Purpose Transistor

### N-Channel

#### Features

- Pb-Free Package is Available

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	25	Vdc
Drain-Gate Voltage	$V_{DG}$	25	Vdc
Reverse Gate-Source Voltage	$V_{GS(r)}$	-25	Vdc
Gate Current	$I_G$	10	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) ( $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$ )	$P_D$	225	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

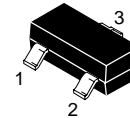
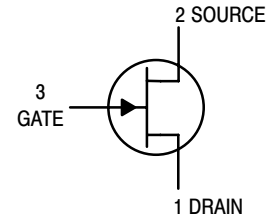
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.



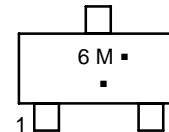
ON Semiconductor®

<http://onsemi.com>



SOT-23 (TO-236)  
CASE 318  
STYLE 10

#### MARKING DIAGRAM



6 = Specific Device Code

M = Date Code\*

■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
MMBF5457LT1	SOT-23	3000/Tape & Reel
MMBF5457LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

# MMBF5457LT1

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Gate-Source Breakdown Voltage ( $I_G = 10 \mu\text{Adc}$ , $V_{DS} = 0$ )	$V_{(BR)GSS}$	-25	-	-	Vdc
Gate Reverse Current ( $V_{GS} = 15 \text{Vdc}$ , $V_{DS} = 0$ ) ( $V_{GS} = 15 \text{Vdc}$ , $V_{DS} = 0$ , $T_A = 100^\circ\text{C}$ )	$I_{GSS}$	-	-	-1.0 -200	nAdc
Gate Source Cutoff Voltage ( $V_{DS} = 15 \text{Vdc}$ , $I_D = 10 \text{nAdc}$ )	$V_{GS(off)}$	-0.5	-	-6.0	Vdc
Gate Source Voltage ( $V_{DS} = 15 \text{Vdc}$ , $I_D = 100 \mu\text{Adc}$ )	$V_{GS}$	-	-2.5	-	Vdc
<b>ON CHARACTERISTICS</b>					
Zero-Gate-Voltage Drain Current (Note 2) ( $V_{DS} = 15 \text{Vdc}$ , $V_{GS} = 0$ )	$I_{DSS}$	1.0	-	5.0	mAdc
<b>SMALL-SIGNAL CHARACTERISTICS</b>					
Forward Transfer Admittance (Note 2) ( $V_{DS} = 15 \text{Vdc}$ , $V_{GS} = 0$ , $f = 1.0 \text{kHz}$ )	$ Y_{fs} $	1000	-	5000	$\mu\text{mhos}$
Output Common Source Admittance ( $V_{DS} = 15 \text{Vdc}$ , $V_{GS} = 0$ , $f = 1.0 \text{kHz}$ )	$ y_{os} $	-	10	50	$\mu\text{mhos}$
Input Capacitance ( $V_{DS} = 15 \text{Vdc}$ , $V_{GS} = 0$ , $f = 1.0 \text{MHz}$ )	$C_{iss}$	-	4.5	7.0	pF
Reverse Transfer Capacitance ( $V_{DS} = 15 \text{Vdc}$ , $V_{GS} = 0$ , $f = 1.0 \text{MHz}$ )	$C_{rss}$	-	1.5	3.0	pF

2. Pulse Test: Pulse Width  $\leq 630 \text{ms}$ , Duty Cycle  $\leq 10\%$ .

# MMBF5457LT1

## TYPICAL CHARACTERISTICS

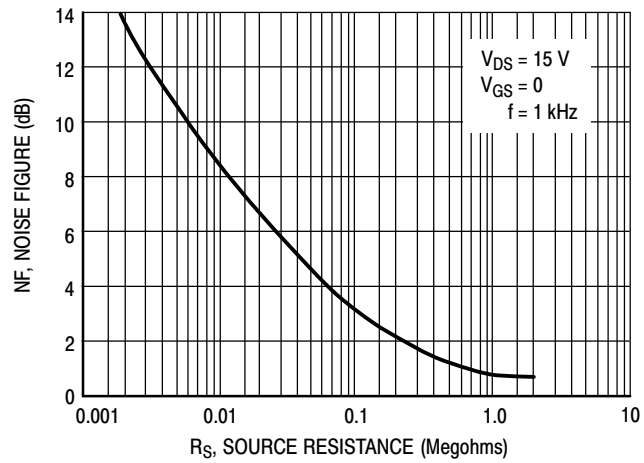


Figure 1. Noise Figure versus Source Resistance

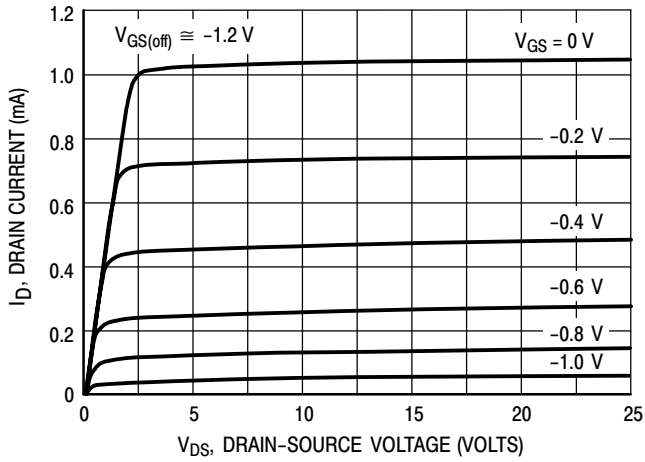


Figure 2. Typical Drain Characteristics

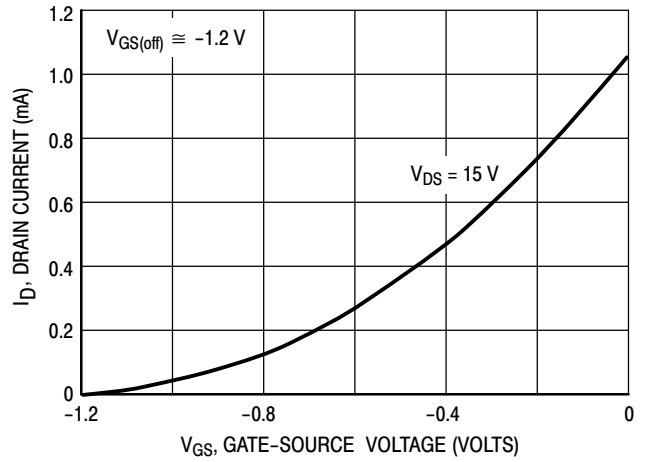


Figure 3. Common Source Transfer Characteristics

# MMBF5457LT1

## TYPICAL CHARACTERISTICS

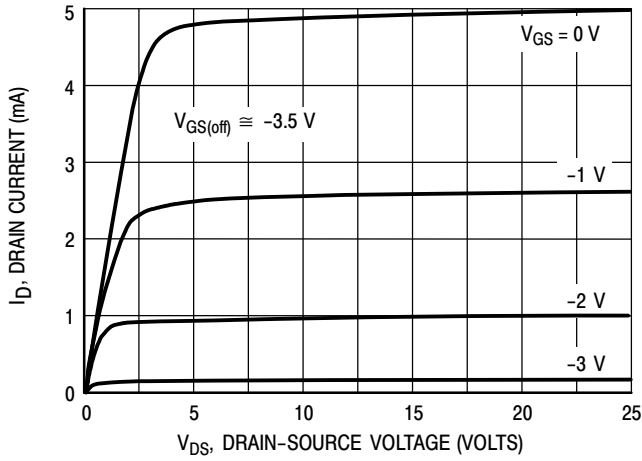


Figure 4. Typical Drain Characteristics

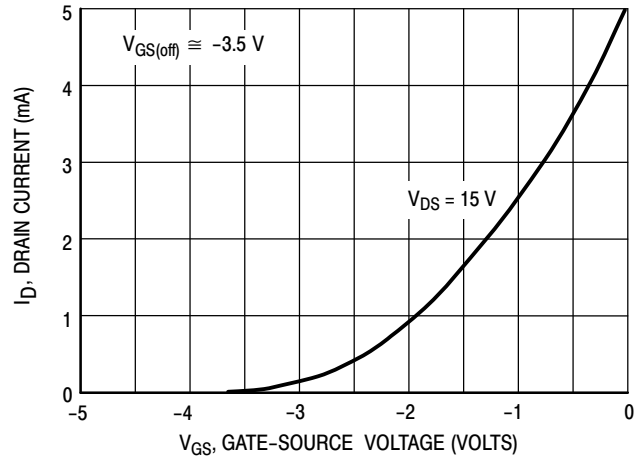


Figure 5. Common Source Transfer Characteristics

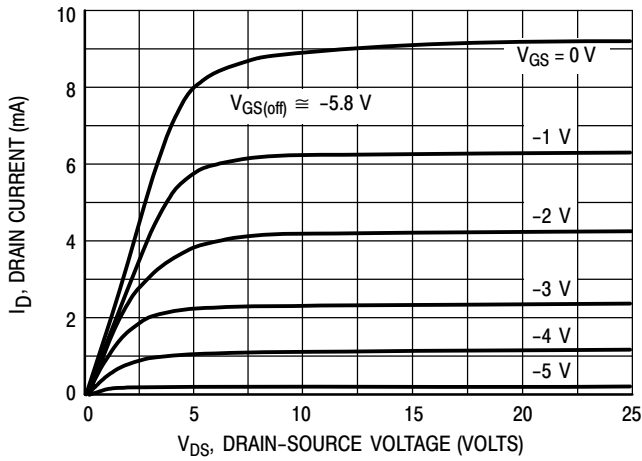


Figure 6. Typical Drain Characteristics

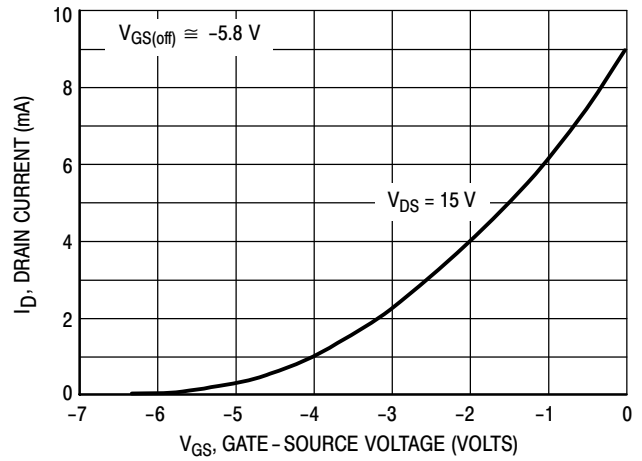


Figure 7. Common Source Transfer Characteristics

Note: Graphical data is presented for dc conditions. Tabular data is given for pulsed conditions (Pulse Width = 630 ms, Duty Cycle = 10%). Under dc conditions, self heating in higher  $I_{DSS}$  units reduces  $I_{DSS}$ .



SCALE 4:1

**SOT-23 (TO-236) 2.90x1.30x1.00 1.90P**  
CASE 318  
ISSUE AU

DATE 14 AUG 2024



MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.89	1.00	1.11
A1	0.01	0.06	0.10
b	0.37	0.44	0.50
c	0.08	0.14	0.20
D	2.80	2.90	3.04
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.43	0.55
L1	0.35	0.54	0.69
HE	2.10	2.40	2.64
T	0°	---	10°

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

**GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**STYLES ON PAGE 2**

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**SOT-23 (TO-236) 2.90x1.30x1.00 1.90P**  
**CASE 318**  
**ISSUE AU**

DATE 14 AUG 2024

STYLE 1 THRU 5:  
CANCELLED

STYLE 6:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

STYLE 7:  
PIN 1. EMITTER  
2. BASE  
3. COLLECTOR

STYLE 8:  
PIN 1. ANODE  
2. NO CONNECTION  
3. CATHODE

STYLE 9:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 10:  
PIN 1. DRAIN  
2. SOURCE  
3. GATE

STYLE 11:  
PIN 1. ANODE  
2. CATHODE  
3. CATHODE-ANODE

STYLE 12:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 13:  
PIN 1. SOURCE  
2. DRAIN  
3. GATE

STYLE 14:  
PIN 1. CATHODE  
2. GATE  
3. ANODE

STYLE 15:  
PIN 1. GATE  
2. CATHODE  
3. ANODE

STYLE 16:  
PIN 1. ANODE  
2. CATHODE  
3. CATHODE

STYLE 17:  
PIN 1. NO CONNECTION  
2. ANODE  
3. CATHODE

STYLE 18:  
PIN 1. NO CONNECTION  
2. CATHODE  
3. ANODE

STYLE 19:  
PIN 1. CATHODE  
2. ANODE  
3. CATHODE-ANODE

STYLE 20:  
PIN 1. CATHODE  
2. ANODE  
3. GATE

STYLE 21:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

STYLE 22:  
PIN 1. RETURN  
2. OUTPUT  
3. INPUT

STYLE 23:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 24:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE

STYLE 25:  
PIN 1. ANODE  
2. CATHODE  
3. GATE

STYLE 26:  
PIN 1. CATHODE  
2. ANODE  
3. NO CONNECTION

STYLE 27:  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE

STYLE 28:  
PIN 1. ANODE  
2. ANODE  
3. ANODE

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